Sierra Components, Inc.
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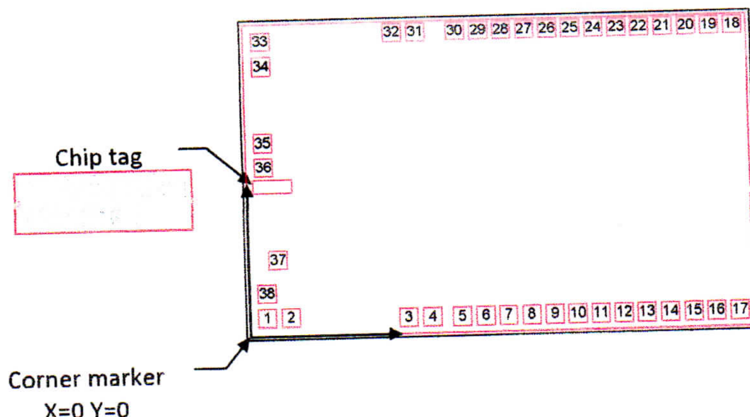
Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



Pin N°	Position	Name	X Coord	Y Coord
1	B1	GND	85	85
2	B2	GND	205	85
3	B3	SOURCE	789	75
4	B4	SOURCE	909	75
5	B5	SOURCE	1055	75
6	B6	SOURCE	1170	75
7	B7	SOURCE	1285	75
8	B8	SOURCE	1400	75
9	B9	SOURCE	1515	75
10	B10	SOURCE	1630	75
11	B11	SOURCE	1745	75
12	B12	SOURCE	1860	75
13	B13	SOURCE	1975	75
14	B14	SOURCE	2090	75
15	B15	SOURCE	2205	75
16	B16	SOURCE	2320	75
17	B17	SOURCE	2435	75
18	T1	DRAIN	2435	1468
19	T2	DRAIN	2320	1468

Pin N°	Position	Name	X Coord	Y Coord
20	T3	DRAIN	2205	1468
21	T4	DRAIN	2090	1468
22	T5	DRAIN	1975	1468
23	T6	DRAIN	1860	1468
24	T7	DRAIN	1745	1468
25	T8	DRAIN	1630	1468
26	T9	DRAIN	1515	1468
27	T10	DRAIN	1400	1468
28	T11	DRAIN	1285	1468
29	T12	DRAIN	1170	1468
30	T13	DRAIN	1055	1468
31	T14	PVDD	861	1468
32	T15	PVDD	741	1468
33	L1	BD_ANODE	85	1435
34	L2	BD_ANODE	85	1315
35	L3	VDD	85	954
36	L4	VDD	85	834
37	L5	IN	146	369
38	L6	GND	85	205

The rear surface of the die (back-gate) is electrically connected to bond pads #3 to #17 (SOURCE).
No current flows through the back-gate.

Top Material: AlCu
Backside Material: Silicon
Bond Pad Size: .004" X .004" min.
Backside Potential: See Notes
Mask Ref: SP-00134-11

APPROVED BY: DK	DIE SIZE .063 X .103"	DATE: 5/13/16
MFG: X-REL.	THICKNESS .011"	P/N: XTR20411B-D